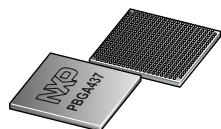


# SOT2180-1

PBGA437, plastic ball grid array, 437 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.37 mm body

12 September 2025

Package information



## 1 Package summary

|                                |                                |
|--------------------------------|--------------------------------|
| Terminal position code         | Q (quad)                       |
| Package type descriptive code  | PBGA437                        |
| Package style descriptive code | PBGA (plastic ball grid array) |
| Package body material type     | P (plastic)                    |
| Mounting method type           | S (surface mount)              |
| Issue date                     | 02-09-2025                     |
| Manufacturer package code      | 98ASA01918D                    |

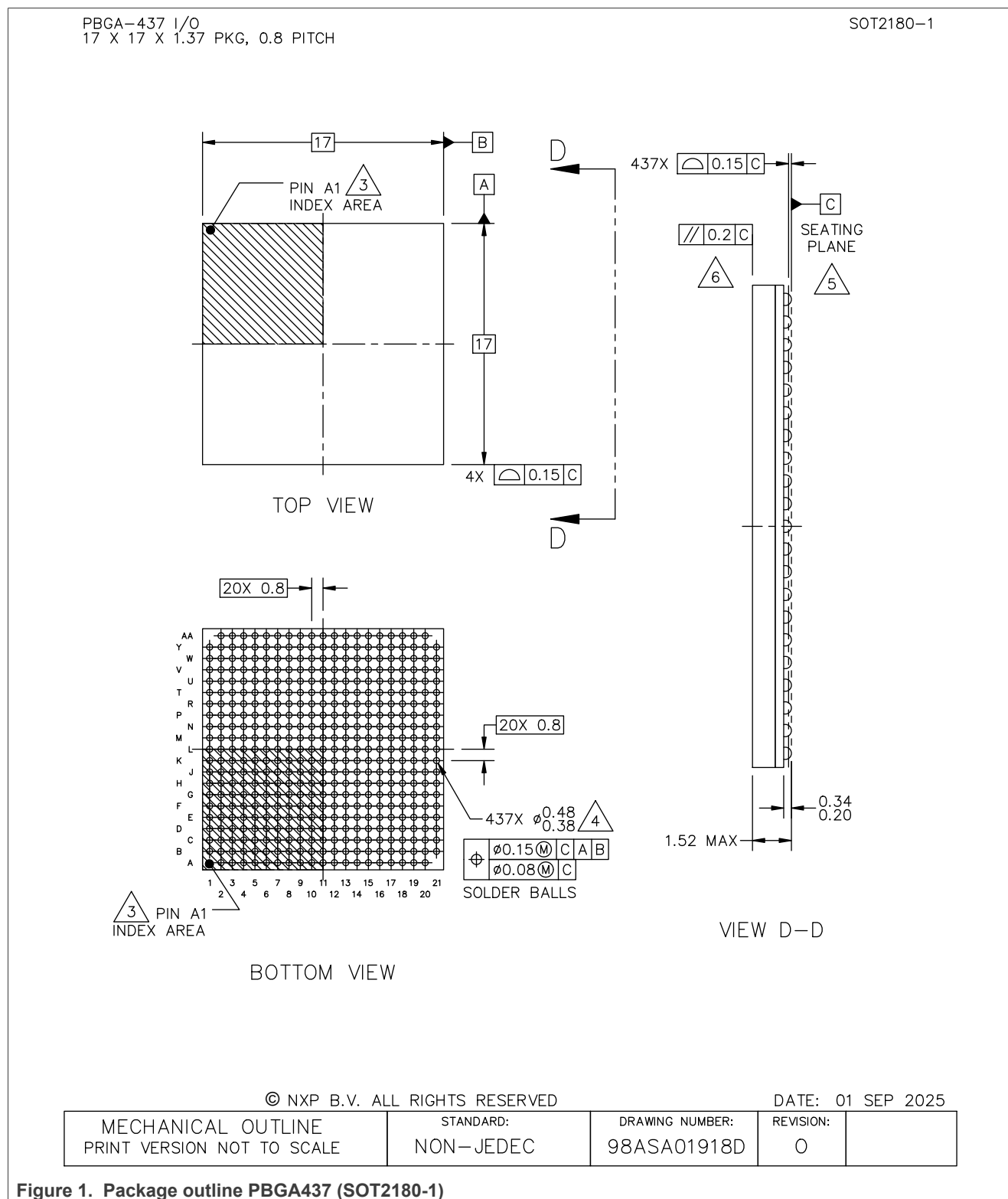
Table 1. Package summary

| Parameter                      | Min   | Nom  | Max   | Unit |
|--------------------------------|-------|------|-------|------|
| package length                 | 16.85 | 17   | 17.15 | mm   |
| package width                  | 16.85 | 17   | 17.15 | mm   |
| package height                 | 1.22  | 1.37 | 1.52  | mm   |
| nominal pitch                  | -     | 0.8  | -     | mm   |
| actual quantity of termination | -     | 437  | -     |      |



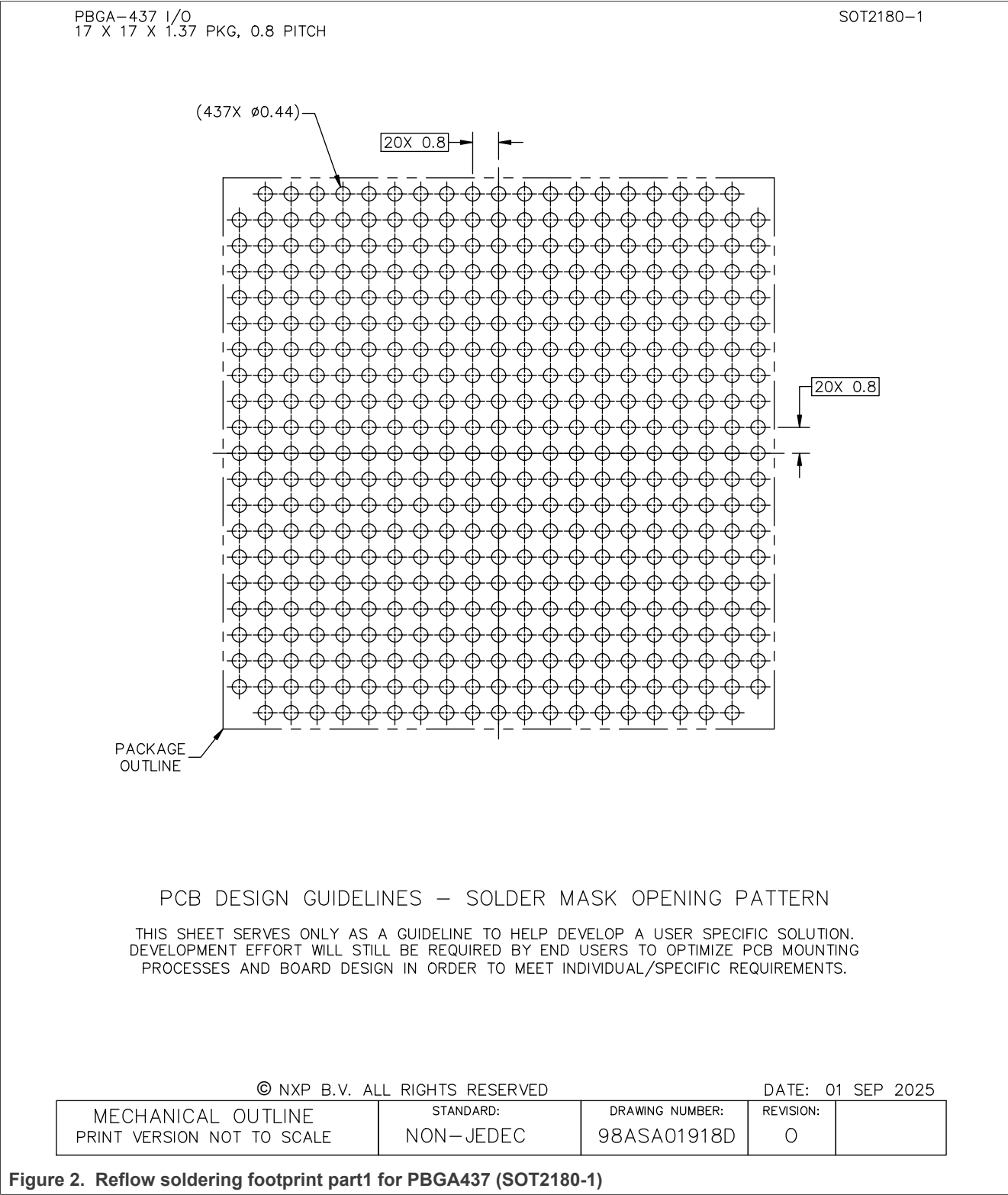
**PBGA437, plastic ball grid array, 437 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.37 mm body**

## 2 Package outline

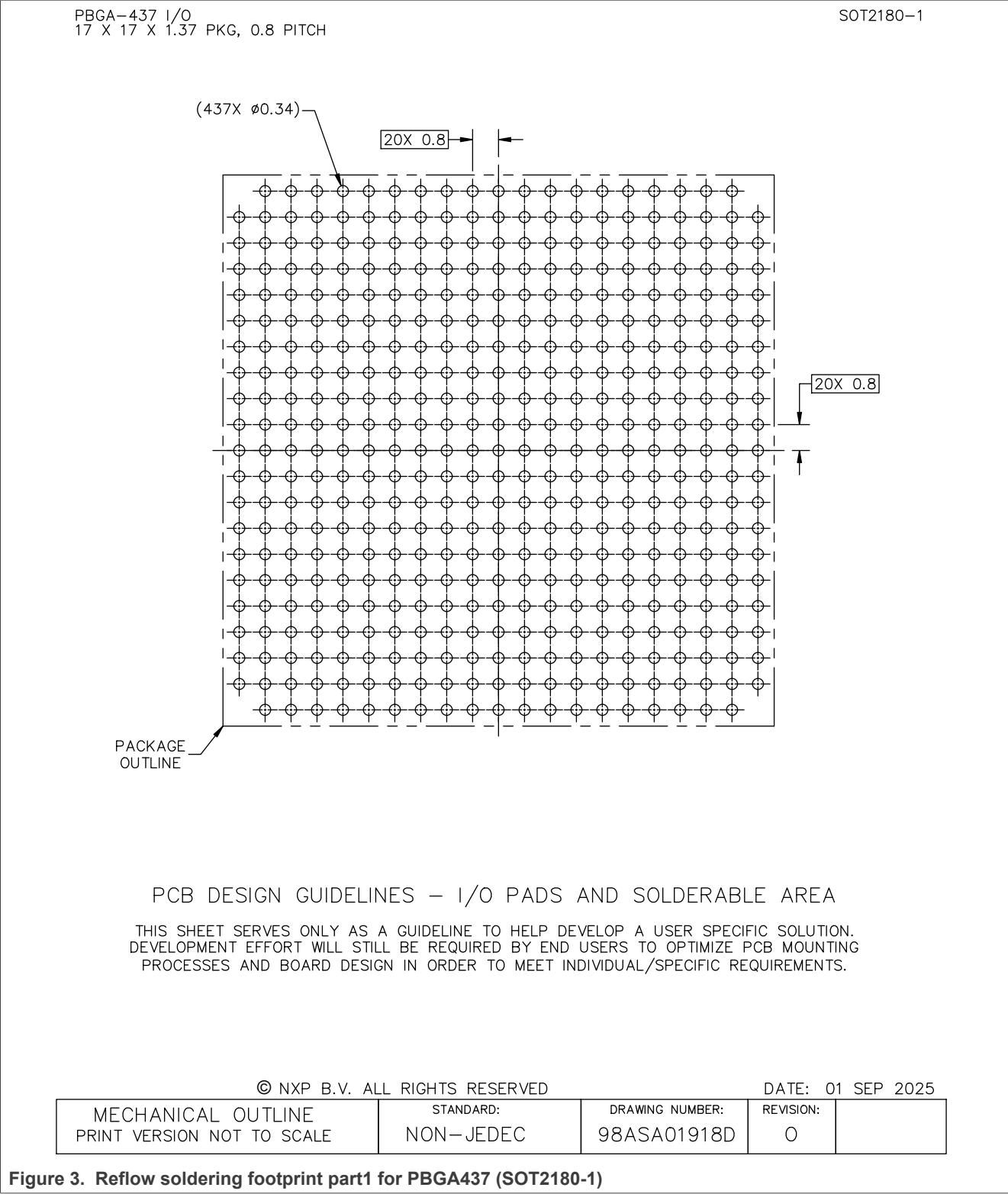


PBGA437, plastic ball grid array, 437 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.37 mm body

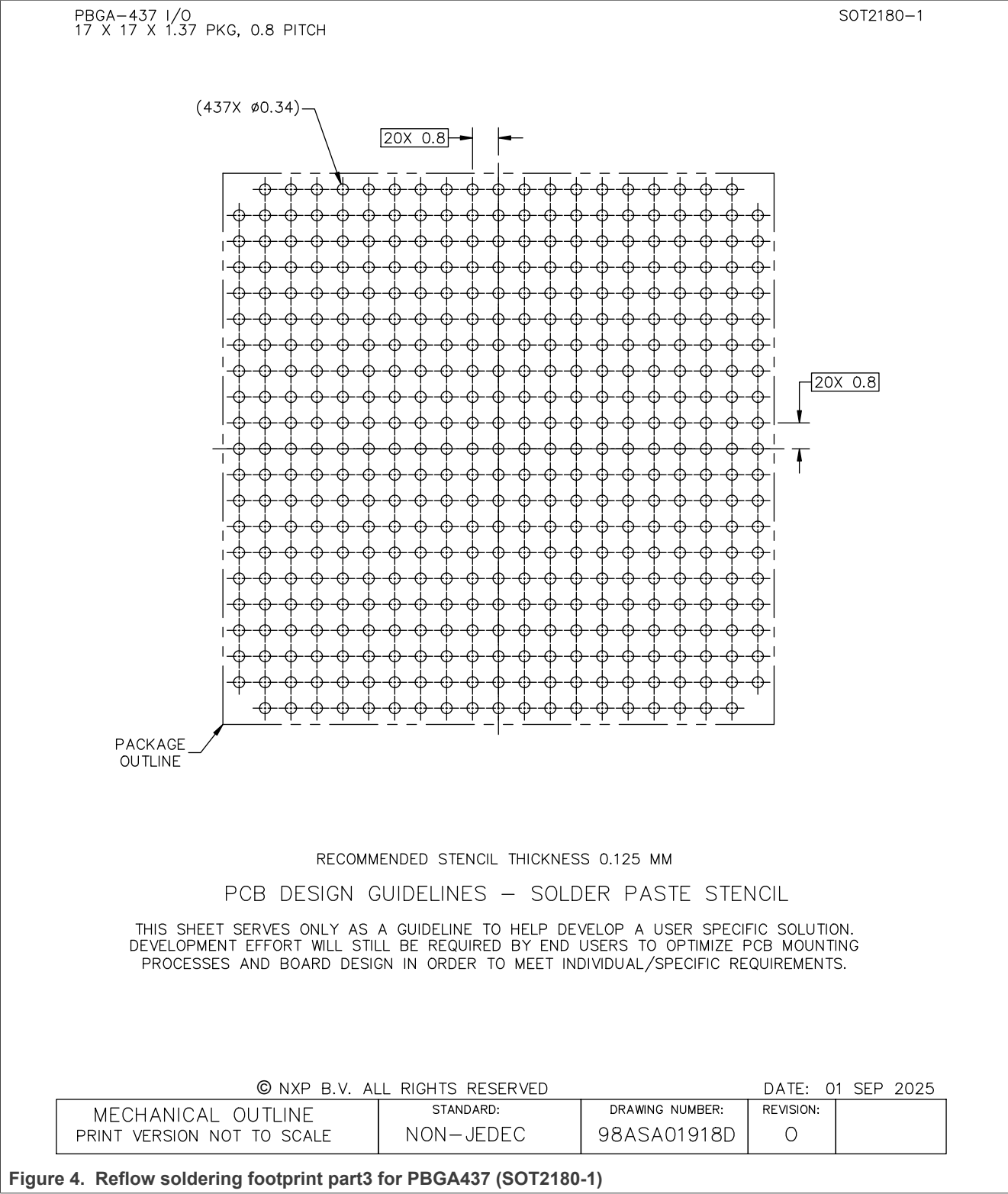
3 Soldering



PBGA437, plastic ball grid array, 437 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.37 mm body



PBGA437, plastic ball grid array, 437 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.37 mm body



PBGA437, plastic ball grid array, 437 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.37 mm body

PBGA-437 I/O  
17 X 17 X 1.37 PKG, 0.8 PITCH

SOT2180-1

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 01 SEP 2025

|                                                  |                        |                                |                |  |
|--------------------------------------------------|------------------------|--------------------------------|----------------|--|
| MECHANICAL OUTLINE<br>PRINT VERSION NOT TO SCALE | STANDARD:<br>NON-JEDEC | DRAWING NUMBER:<br>98ASA01918D | REVISION:<br>0 |  |
|--------------------------------------------------|------------------------|--------------------------------|----------------|--|

Figure 5. Package outline note PBGA437 (SOT2180-1)

## 4 Legal information

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PBGA437, plastic ball grid array, 437 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.37 mm body

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